



MDT Electronics

Patch Panel, 3x8 Hedgehog Status

Prototype patch panels built and installed on EIL pre-prototype in Boston

Several changes are needed before production:

- Change connector type lower-profile to clear mezzanine board

- Change cable shield wiring scheme (pending final test results)

- Change external data cable (TDC Link cable) to new (as yet undetermined) shielded type

Updated layout will be completed soon (by 15-May)

3x8 Signal Hedgehog Board Status:

- 80 boards in stock at B.U.

- 200 more boards (completing Module-0 requirements) due by 12 May

- US Production order for 600 boards placed 1-May

NOTE: no production beyond Module-0 for European chambers has yet been scheduled.